

C4400UF

Conductor

Description

C4400UF is an unfritted silver used primarily in multilayer applications as a top layer conductor to provide a glass free surface. C4400UF offers a highly reliable dense film which exhibits excellent solderability. C4400UF is Al wire bondable.

Key Features

- Pure Ag Conductor overprint Enhances solderability Al wire bondable



This picture does not show the packaging of C4400UF and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≥ 3.0 milliohms/square at 12 microns fired film thickness
Viscosity	220-280 Kcps Brookfield HBT, SC4-14 spindle and 6R utility cup @ 10 rpm, 25°C.
Solids	82.5 ±1%
Alloy Ratio	100
Metal	Ag
Color	Silver

Recommended Processing Guide

Process Temperature (TDS)	850°C peak temperature Dwell time of 6 to 10 minutes
Film Thickness	10 – 14 µm

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Warranty

6 months

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